

Amendments to the Specification

Please replace the paragraph beginning on page 26, line 15, with the following rewritten paragraph:

Since depressions are formed instead of through-holes in the substrate for a semiconductor device in accordance with this embodiment of the invention, there is no seepage of resin provided on one face of the substrate to the opposite side an opposing face of the substrate when resin is provided. This substrate for a semiconductor device could be used to fabrication fabricate a semiconductor chip mounting substrate. Semiconductor devices could be fabricated by cutting apart this semiconductor chip mounting substrate. The methods described above with reference to the previous embodiments can be applied thereto. Since the cutting is done through the depressions instead of through-holes, the cutting ends at portions that have become thinner, so there is little cutting dust.